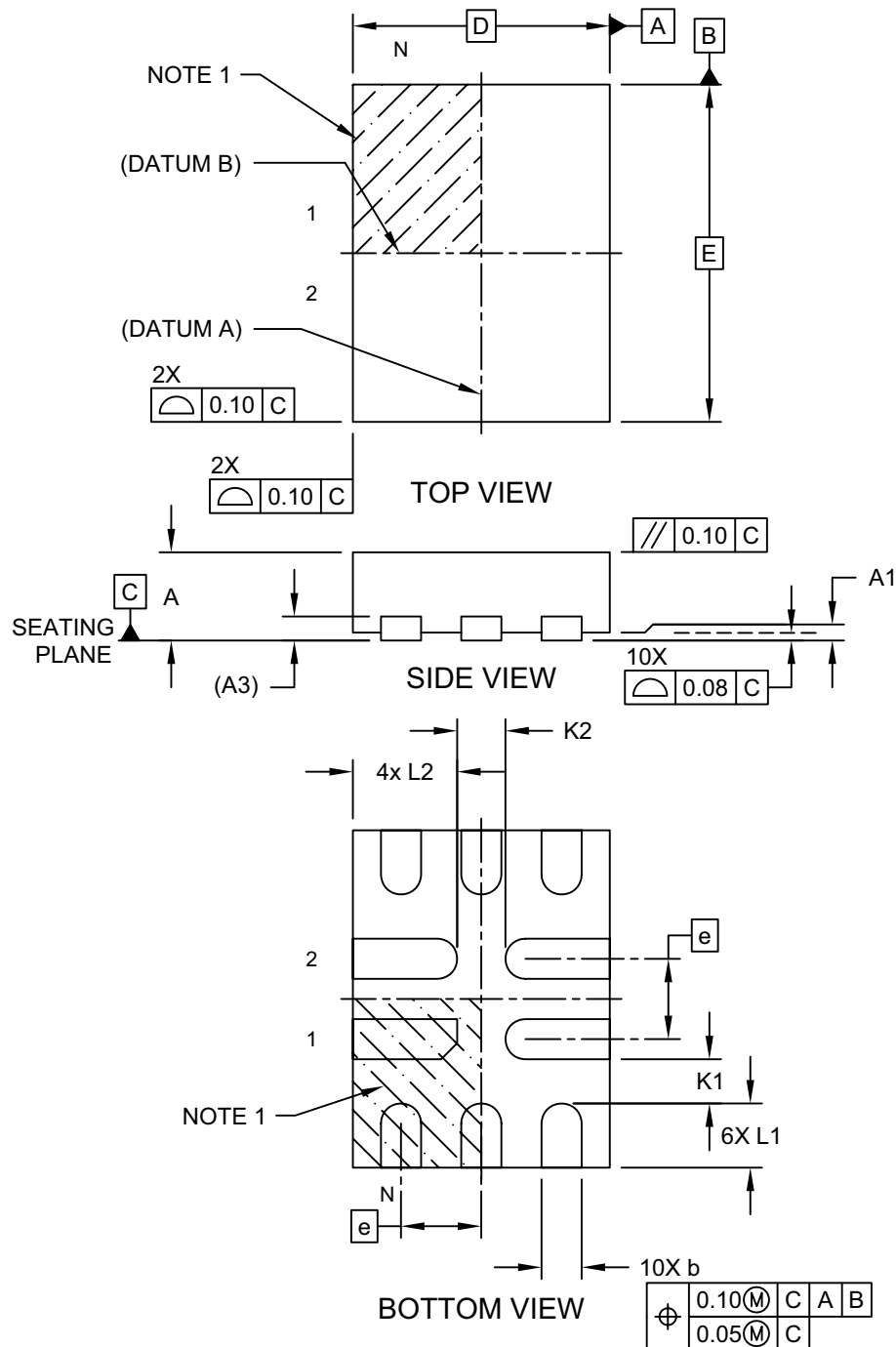


10-Lead Ultra Thin Plastic Quad Flat, No Lead Package (3V) - 1.6x2.1 mm Body [UQFN] Chip-On-Lead

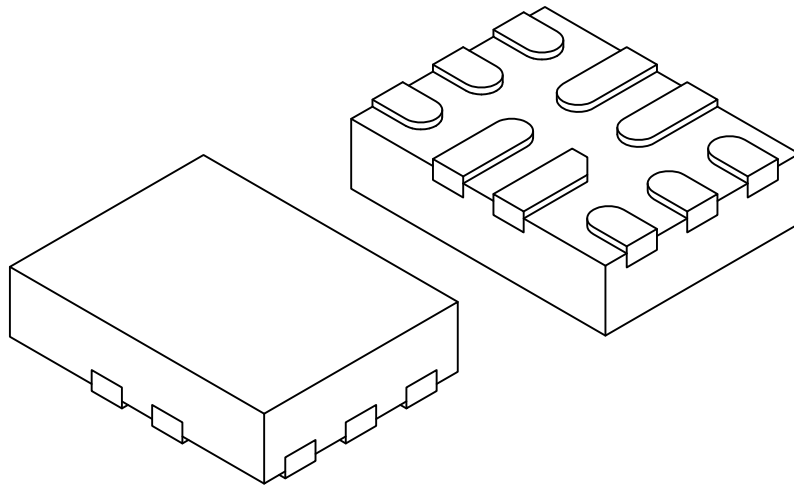
Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing C04-379A Sheet 1 of 2

10-Lead Ultra Thin Plastic Quad Flat, No Lead Package (3V) - 1.6x2.1 mm Body [UQFN] Chip-On-Lead

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N	10		
Pitch	e	0.50 BSC		
Overall Height	A	0.50	0.55	0.60
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	(A3)	0.127 REF		
Overall Width	E	2.10 BSC		
Overall Length	D	1.60 BSC		
Terminal Width	b	0.20	0.25	0.30
Terminal Length	L1	0.35	0.40	0.45
Terminal Length	L2	0.60	0.65	0.70
Terminal Clearance	K1	0.20	-	-
Terminal Clearance	K2	0.20	-	-

Notes:

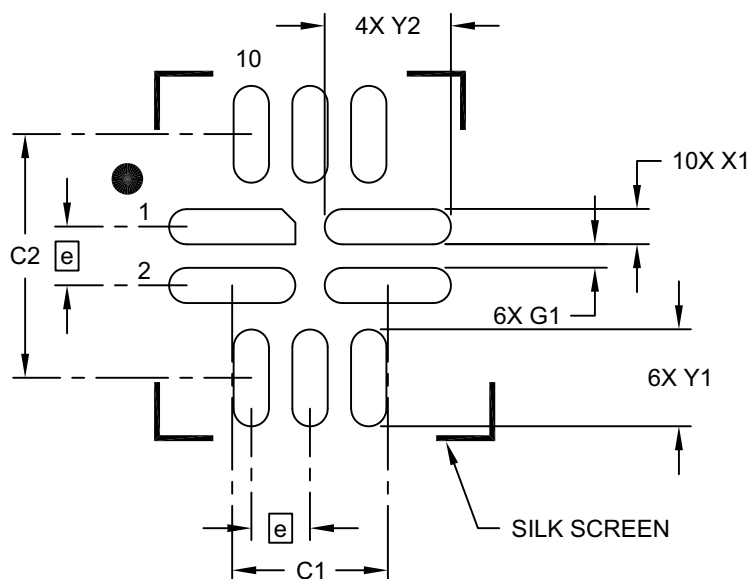
- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated
- Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

10-Lead Ultra Thin Plastic Quad Flat, No Lead Package (3V) - 1.6x2.1 mm Body [UQFN] Chip-On-Lead

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Contact Pad Spacing	C1		1.325	
Contact Pad Spacing	C2		2.075	
Contact Pad Width (X10)	X1			0.30
Contact Pad Length (X6)	Y1			0.825
Contact Pad Length (X4)	Y2			1.075
Contact Pad to Center Pad (X6)	G1	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.